TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π–MOSV)

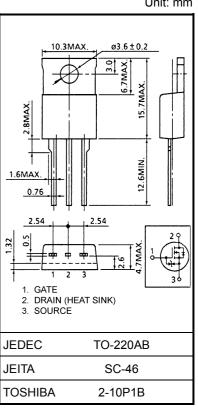
2SK2542

Switching Regulator Applications

- 4 V gate drive
- Low drain-source ON resistance $: R_{DS} (ON) = 0.75 \Omega (typ.)$
- High forward transfer admittance $: |Y_{fs}| = 7.0 \text{ S (typ.)}$
- Low leakage current : $I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 500 \ V)$ •
- : $V_{th} = 2.0 \sim 4.0 V (V_{DS} = 10 V, I_D = 1 mA)$ Enhancement-mode

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	500	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	500	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	۱ _D	8	А	
	Pulse (Note 1)	I _{DP}	32	А	
Drain power dissipation	on (Tc = 25°C)	PD	80	W	
Single pulse avalanche energy (Note 2)		E _{AS}	312	mJ	
Avalanche current		I _{AR}	8	А	
Repetitive avalanche energy (Note 3)		E _{AR}	8	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature r	ange	T _{stg}	-55~150	°C	



Weight: 2.0 g (typ.)

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	1.56	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	83.3	°C / W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 8.3 mH, R_G = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating: Pulse width limited by maximum channel temperature

This transistor is an electrostatic sensitive device. Please handle with caution.

Unit: mm

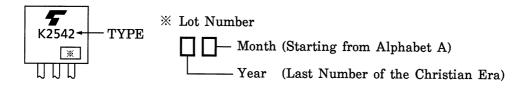
Electrical Characteristics (Ta = 25°C)

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I _{GSS}	V_{GS} = ±25 V, V_{DS} = 0 V	_	_	±10	μA
Gate-source bre	eakdown voltage	V (BR) GSS	I _G = ±10 μA, V _{GS} = 0 V	±30	_	_	V
Drain cut-off cu	rrent	I _{DSS}	V _{DS} = 500 V, V _{DS} = 0 V	_	—	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	—	—	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	—	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A	_	0.75	0.85	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 4 A	3.5	7.0	—	S
Input capacitance	e	C _{iss}		_	1300	—	
Reverse transfe	Reverse transfer capacitance C_{rss} V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz		_	130	—	pF	
Output capacitance		C _{oss}		_	400	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 \text{ V}}{}_{0 \text{ V}} \int I_{D} = 4 \text{ A} \\ \downarrow \qquad \qquad$	_	26	_	
	Turn-on time	t _{on}		_	45	_	20
	Fall time	t _f		_	40	_	ns
	Turn-off time	t _{off}	Duty $\leq 1\%$, t _w = 10 µs	_	140	_	
Total gate charge (Gate-source plus gate-drain)		Qg			30	_	_
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 8 A		17	—	nC
Gate-drain ("miller") charge		Q _{gd}			13	_	

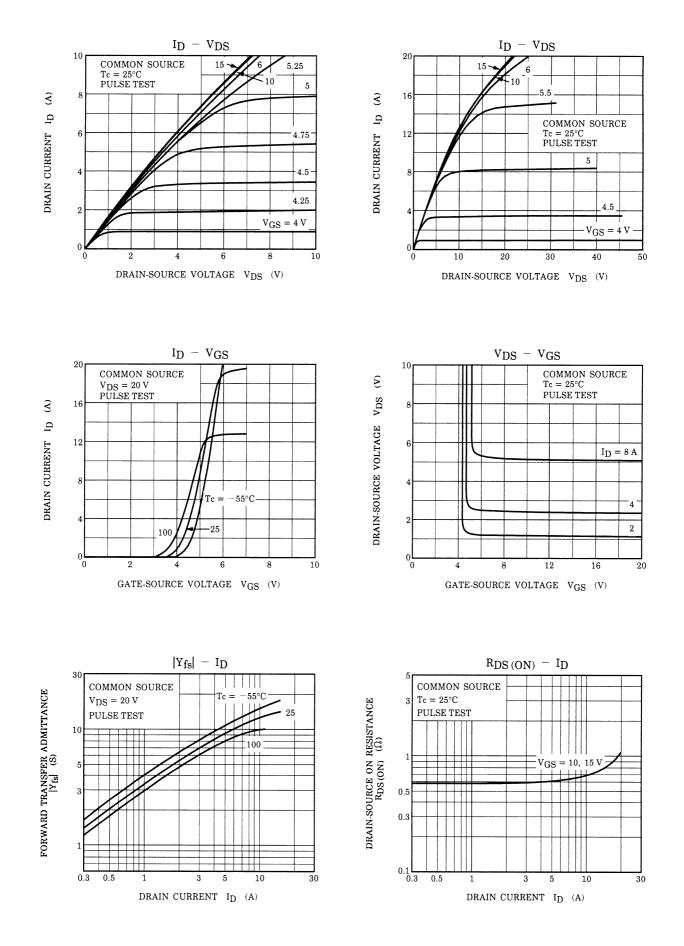
Source–Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	8	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	32	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 8 A, V _{GS} = 0 V		_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 8 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μs		1200	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / μs	_	10	_	μC

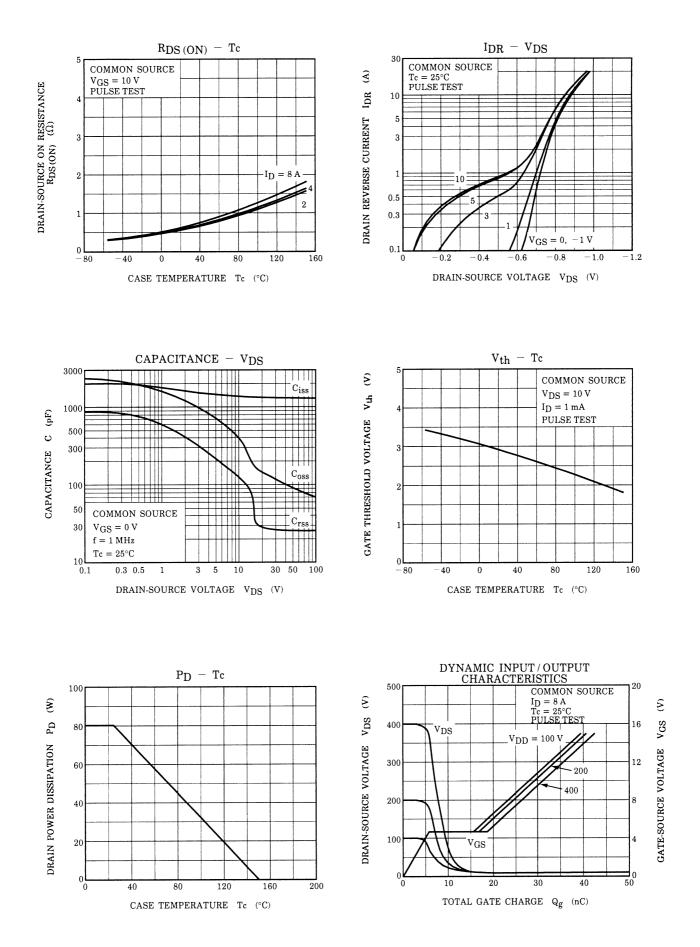
Marking

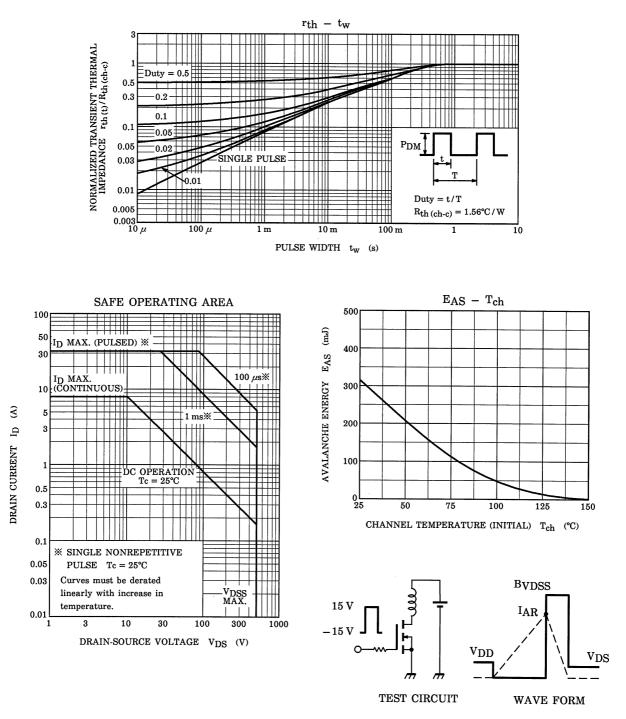


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 $R_{G} = 25 \Omega$ $V_{DD} = 90 \text{ V}, L = 8.3 \text{ mH}$ $EAS = \frac{1}{2} \cdot L \cdot I^{2} \cdot \left(\frac{BVDSS}{BVDSS - VDD}\right)$

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